

Bis(4-Chlorophenylsulphonyl)methane

Inchi: InChI=1S/C13H10Cl2O4S2/c14-10-1-5-12(6-2-10)20(16,17)9-21(18,19)13-7-3-11(15)4-8
InchiKey: UQLKRAFFXYZVBU-UHFFFAOYSA-N
Formula: C13H10Cl2O4S2
SMILES: O=S(=O)(CS(=O)(=O)c1ccc(Cl)cc1)c1ccc(Cl)cc1
Mol. weight [g/mol]: 365.26

Physical Properties

Property code	Value	Unit	Source
hf	-478.52	kJ/mol	Cheméo Relay (1.0)
hfus	47.88	kJ/mol	Joback Method
hvap	133.05	kJ/mol	Cheméo Relay (1.0)
ie	8.92	eV	Cheméo Relay (1.0)
log10ws	-4.48		Cheméo Relay (1.0)
logp	3.199		Crippen Method
mcvol	227.170	ml/mol	McGowan Method
tb	692.76	K	Cheméo Relay (1.0)
tf	443.61	K	Cheméo Relay (1.0)

Temperature Dependent Properties

Property code	Value	Unit	Temperature [K]	Source
cpg	541.86	J/mol×K	730.58	Joback Method
cpg	554.26	J/mol×K	769.08	Joback Method
cpg	565.37	J/mol×K	807.58	Joback Method
cpg	575.19	J/mol×K	846.07	Joback Method
cpg	583.74	J/mol×K	884.57	Joback Method
cpg	591.04	J/mol×K	923.07	Joback Method
cpg	597.08	J/mol×K	961.57	Joback Method

Sources

Joback Method:	https://en.wikipedia.org/wiki/Joback_method
McGowan Method:	http://link.springer.com/article/10.1007/BF02311772
Crippen Method:	http://pubs.acs.org/doi/abs/10.1021/ci990307l
Crippen Method:	https://www.chemeo.com/doc/models/crippen_log10ws
Cheméo Relay (1.0):	
Cheméo Relay (1.0, beta):	
NIST Webbook:	http://webbook.nist.gov/cgi/cbook.cgi?ID=C2394027&Units=SI

Legend

cpg:	Ideal gas heat capacity
hf:	Enthalpy of formation at standard conditions
hfus:	Enthalpy of fusion at standard conditions
hvap:	Enthalpy of vaporization at standard conditions
ie:	Ionization energy
log10ws:	Log10 of Water solubility in mol/l
logp:	Octanol/Water partition coefficient
mcvol:	McGowan's characteristic volume
tb:	Normal Boiling Point Temperature
tf:	Normal melting (fusion) point

Latest version available from:

<https://www.chemeo.com/cid/34-856-4/Bis-4-Chlorophenylsulphonyl-methane.pdf>

Generated by Cheméo on 2026-07-21 18:11:13.108194287 +0000 UTC m=+168568.950079649.

Cheméo (<https://www.chemeo.com>) is the biggest free database of chemical and physical data for the process industry.